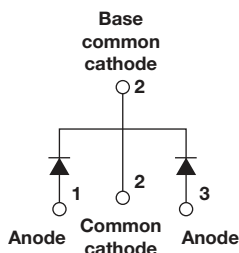


# HEXFRED® Ultrafast Soft Recovery Diode, 2 x 8 A



TO-263AB (D²PAK)



## FEATURES

- Ultrafast and ultrasoft recovery
- Very low  $I_{RRM}$  and  $Q_{rr}$
- Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

## DESCRIPTION

VS-HFA16TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 8 A per leg continuous current, the VS-HFA16TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current ( $I_{RRM}$ ) and does not exhibit any tendency to “snap-off” during the  $t_b$  portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA16TA60CS is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

## PRODUCT SUMMARY

Package	TO-263AB (D²PAK)
$I_{F(AV)}$	2 x 8 A
$V_R$	600 V
$V_F$ at $I_F$	1.4 V
$t_{rr}$ (typ.)	18 ns
$T_J$ max.	150 °C
Diode variation	Common cathode

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_R$		600	V
Maximum continuous forward current <span style="float:right">per leg</span> <span style="float:right">per device</span>	$I_F$	$T_C = 100\text{ °C}$	8 16	A
Single pulse forward current	$I_{FSM}$		60	
Maximum repetitive forward current	$I_{FRM}$		24	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	36	W
		$T_C = 100\text{ °C}$	14	
Operating junction and storage temperature range	$T_J, T_{Stg}$		-55 to +150	°C



ELECTRICAL SPECIFICATIONS PER LEG ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Cathode to anode breakdown voltage	$V_{BR}$	$I_R = 100\text{ }\mu\text{A}$		600	-	- V
Maximum forward voltage	$V_{FM}$	$I_F = 8.0\text{ A}$	See fig. 1	-	1.4	1.7
		$I_F = 16\text{ A}$		-	1.7	2.1
		$I_F = 8.0\text{ A}, T_J = 125\text{ }^{\circ}\text{C}$		-	1.4	1.7
Maximum reverse leakage current	$I_{RM}$	$V_R = V_R\text{ rated}$	See fig. 2	-	0.3	5.0
		$T_J = 125\text{ }^{\circ}\text{C}, V_R = 0.8 \times V_R\text{ rated}$		-	100	500 $\mu\text{A}$
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	See fig. 3	-	10	25 pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body		-	8.0	- nH

DYNAMIC RECOVERY CHARACTERISTICS PER LEG ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Reverse recovery time See fig. 5, 6 and 16	$t_{rr}$	$I_F = 1.0\text{ A}, dI_F/dt = 200\text{ A}/\mu\text{s}, V_R = 30\text{ V}$		-	18	- ns
	$t_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$	$I_F = 8.0\text{ A}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $V_R = 200\text{ V}$	-	37	55
	$t_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$		-	55	90
Peak recovery current See fig. 7 and 8	$I_{RRM1}$	$T_J = 25\text{ }^{\circ}\text{C}$		-	3.5	5.0 A
	$I_{RRM2}$	$T_J = 125\text{ }^{\circ}\text{C}$		-	4.5	8.0
Reverse recovery charge See fig. 9 and 10	$Q_{rr1}$	$T_J = 25\text{ }^{\circ}\text{C}$		-	65	138 nC
	$Q_{rr2}$	$T_J = 125\text{ }^{\circ}\text{C}$		-	124	360
Peak rate of fall of recovery current during $t_b$ See fig. 11 & 12	$dI_{(rec)M}/dt1$	$T_J = 25\text{ }^{\circ}\text{C}$		-	240	- $\text{A}/\mu\text{s}$
	$dI_{(rec)M}/dt2$	$T_J = 125\text{ }^{\circ}\text{C}$		-	210	-

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX. UNITS
Lead temperature	$T_{lead}$	0.063" from case (1.6 mm) for 10 s		-	-	300 $^{\circ}\text{C}$
Junction to case, single leg conducting	$R_{thJC}$			-	-	3.5
Junction to case, both legs conducting				-	-	1.75 K/W
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount		-	-	80
Weight				-	2	- g
				-	0.07	- oz.
Mounting torque				6.0 (5.0)	-	12 (10) $\text{kgf} \cdot \text{cm}$ ( $\text{lbf} \cdot \text{in}$ )
Marking device		Case style TO-263AB (D <sup>2</sup> PAK)		HFA16TA60CS		

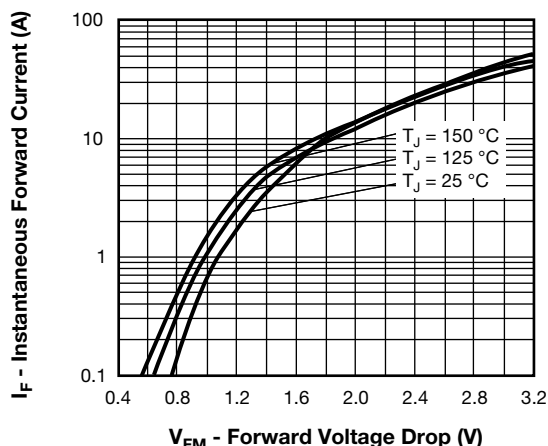


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

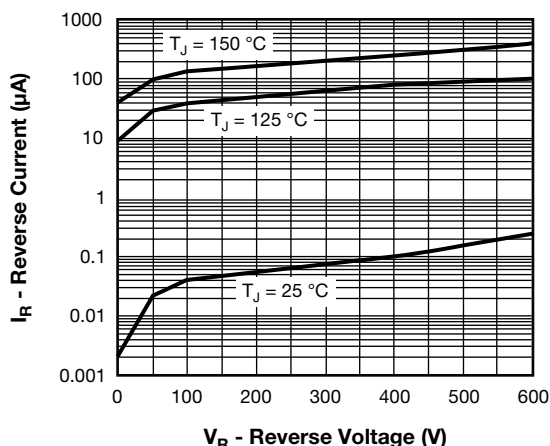


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

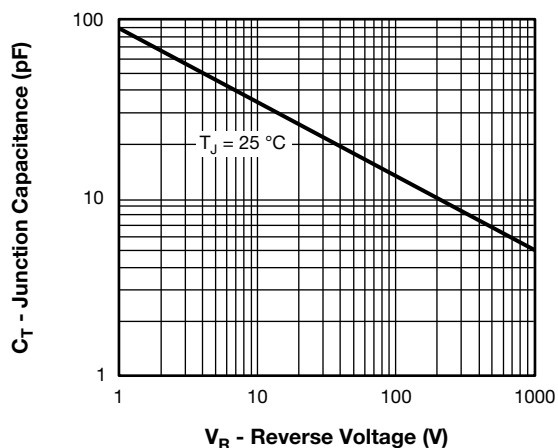


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

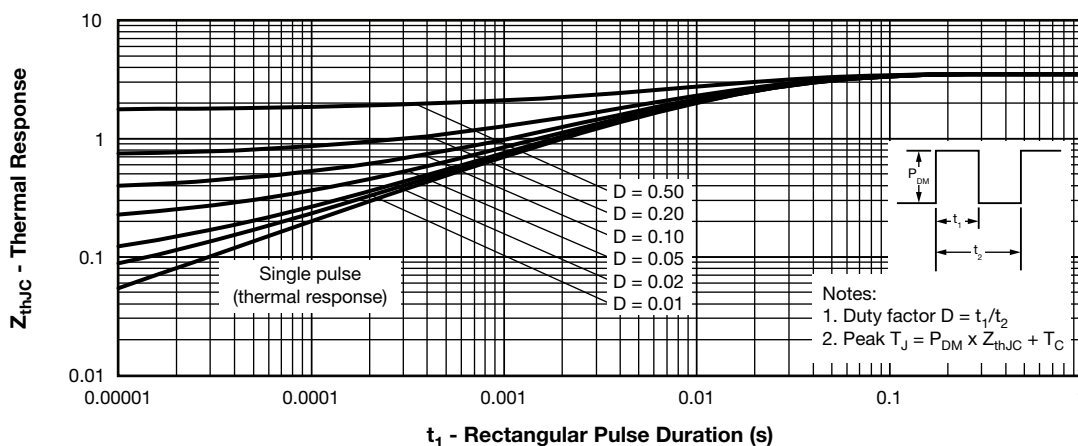


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)

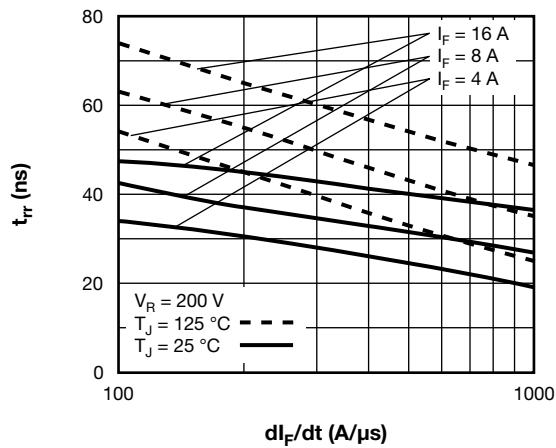


Fig. 5 - Typical Reverse Recovery Time vs.  $di_F/dt$  (Per Leg)

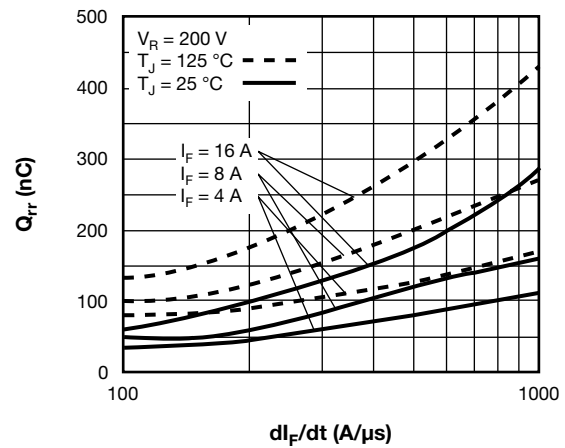


Fig. 7 - Typical Stored Charge vs.  $di_F/dt$  (Per Leg)

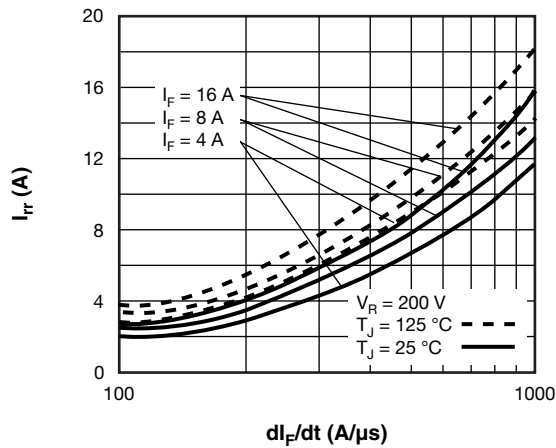


Fig. 6 - Typical Recovery Current vs.  $di_F/dt$  (Per Leg)

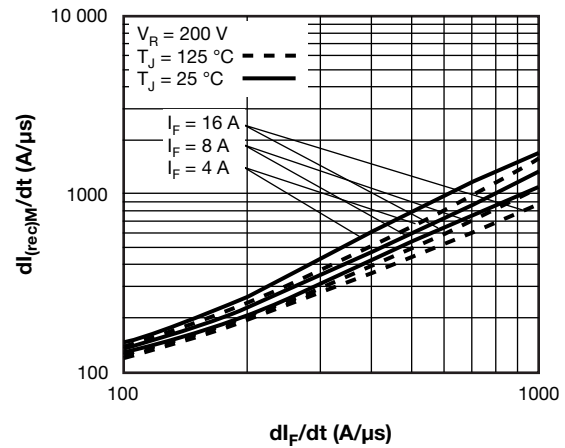


Fig. 8 - Typical  $di_{(rec)M}/dt$  vs.  $di_F/dt$  (Per Leg)

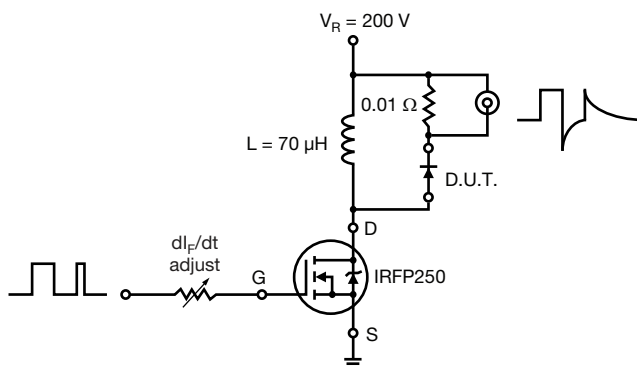


Fig. 9 - Reverse Recovery Parameter Test Circuit

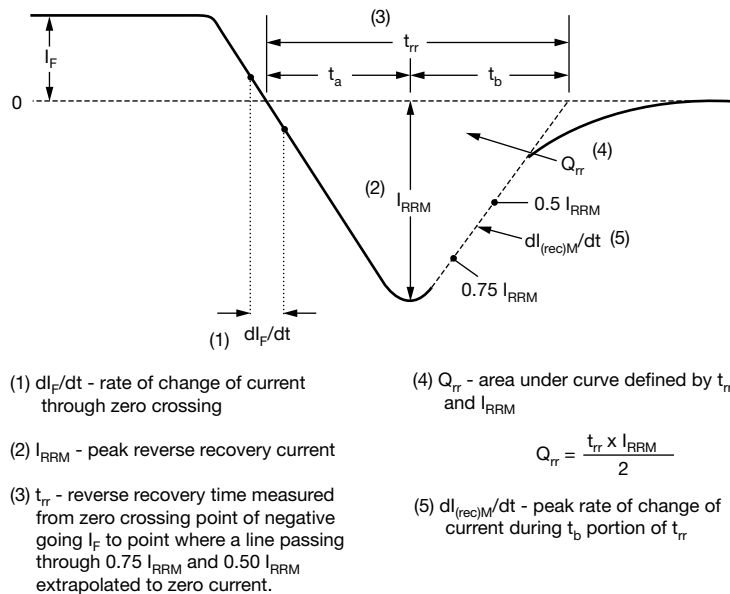


Fig. 10 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>HF</b>	<b>A</b>	<b>16</b>	<b>TA</b>	<b>60</b>	<b>C</b>	<b>S</b>	<b>TRL</b>	<b>PbF</b>
	1	2	3	4	5	6	7	8	9	10

- |           |   |  |
|-----------|---|--|
| <b>1</b>  | - | Vishay Semiconductors product  |
| <b>2</b>  | - | HEXFRED® family  |
| <b>3</b>  | - | Process designator: A = electron irradiated  |
| <b>4</b>  | - | Current rating (16 = 16 A)   |
| <b>5</b>  | - | Package outline (TA = TO-220, 3 leads)   |
| <b>6</b>  | - | Voltage rating (60 = 600 V)  |
| <b>7</b>  | - | Circuit configuration (C = common cathode)   |
| <b>8</b>  | - | S = D <sup>2</sup> PAK   |
| <b>9</b>  | - | <ul style="list-style-type: none"><li>• None = tube</li><li>• TRL = tape and reel (left oriented)</li><li>• TRR = tape and reel (right oriented)</li></ul> |
| <b>10</b> | - | <ul style="list-style-type: none"><li>• PbF = lead (Pb)-free</li><li>• P = lead (Pb)-free (for D<sup>2</sup>PAK TRR and TRL)</li></ul>                     |

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95046">www.vishay.com/doc?95046</a>
Part marking information	<a href="http://www.vishay.com/doc?95054">www.vishay.com/doc?95054</a>
Packaging information	<a href="http://www.vishay.com/doc?95032">www.vishay.com/doc?95032</a>

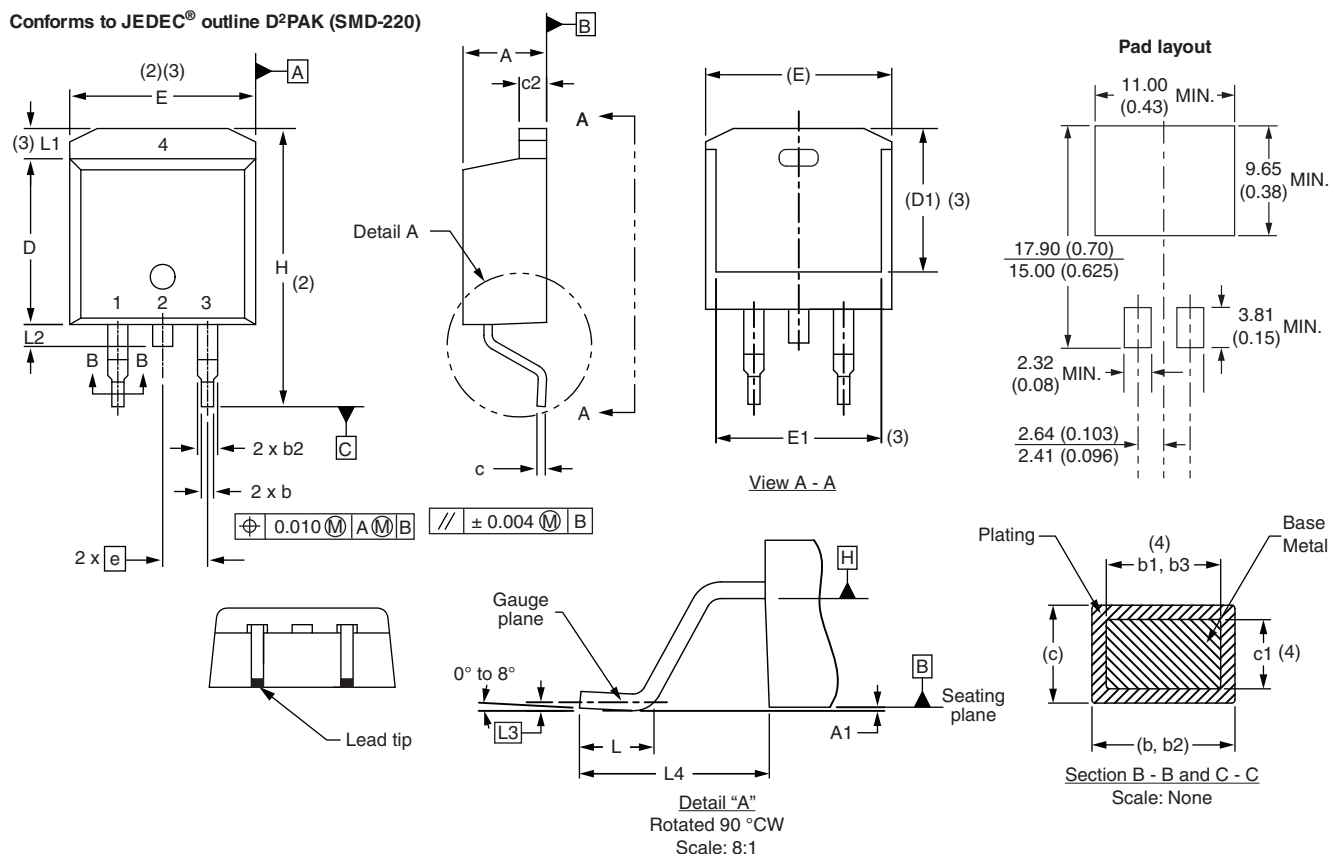
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA16TA60CSPBF	50	1000	Antistatic plastic tube
VS-HFA16TA60CSTRRP	800	800	13" diameter reel
VS-HFA16TA60CSTRLP	800	800	13" diameter reel



## D<sup>2</sup>PAK

### DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D<sup>2</sup>PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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